



3D 锡膏测厚仪

3D SOLDER PASTE INSPECTOR



超强分析
Super analysis



精巧平台
Exquisite platform



激光焊接机身
Laser welding



真实 3D
Realistic 3D



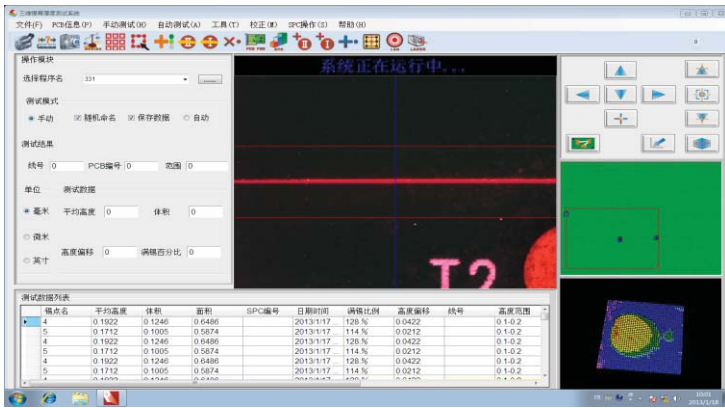
RX 320

3D锡膏测厚仪

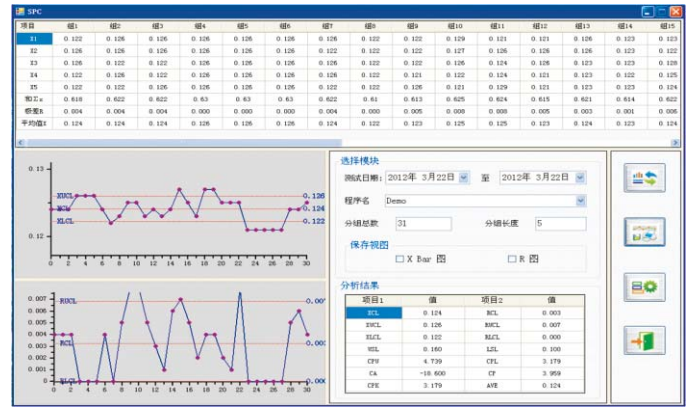
3D SOLDER PASTE INSPECTOR



软件界面/Software interface



SPC 界面/Spc interface



特点/Feature

1. 采用原装德国进口高清彩色相机，保证测试的高精度和高稳定性。
2. 采用军用级别的二级激光，降低外界环境光源的干扰，更加稳定，使用寿命更长。
3. 采用灵活的硬件设计，可调光源、激光和相机，可对不同颜色的PCB板进行测试。
4. 自动夹板功能，快速夹板定位，无须手动操作、调整快速，可视操作更简便，真正可编程测试系统。
5. 通过PCB MARK自动寻找检查位置并矫正偏移。
6. 采用3轴自动对焦、移动，自动补偿修正基板翘曲变形，获取精确锡膏高度。
7. 软件分析条件基于数据库，根据分析条件实现预警功能，直观易懂。
8. 强大的报表分析功能，自动生成R-Chart, X-Bar,自动计算CPK。
9. 导出详细完整的SPC报表，完全避免手写报表的各种弊端。
10. 软件采用简单实用的理念，侧重于测试的高精度设计，校正块重复精度达到正负0.003mm。

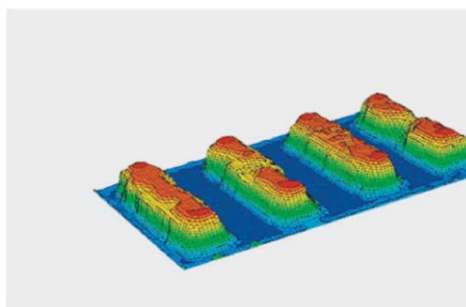
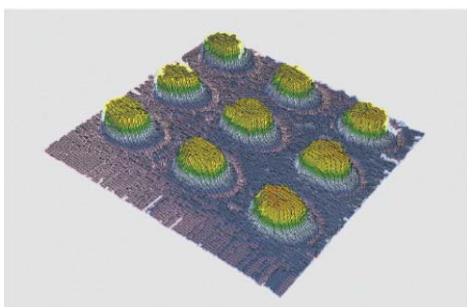
1. Original German sharp color camera to guarantee the high accuracy and high stability of the test.
2. With military grade secondary laser to reduce the interference of external environment light sources, more stable and longer service life.
3. A flexible hardware design, adjustable light laser and camera, can test different colors of PCB.
4. Automatic clamp function, quick clamp positioning without manually, rapid and accurate adjustment, real programmable test system.
5. Automatically find and check the location to rectify deviation by PCB mark.
6. Automatic compensate and correct the warping and deformation of base plate to obtain accurate solder paste height by using three axis move automatically.
7. Software analysis conditions based on the database, according to the analysis conditions to realize the early pre function, intuitive and easy to understand.
8. Powerful reports analysis, automatically generate R-Chart and X-Bar, automatically calculate CPK.
9. Export the complete and detail SPC report, completely avoid disadvantages of written reports.
10. Software with simple and practical idea, focus on the high precision design, the repetitive accuracy of standard block reaches plus or minus 0.003 mm.

技术参数/Technical parameters

1. 最高测量精度：0.001MM
2. 重复精度：±0.005MM
3. 镜头放大倍率：3X
4. 光学检测系统：彩色130万像素CCD
5. 激光镭射系统：红光激光模组
6. 平台系统：全自动
7. 平台尺寸：350x450
8. 测量原理：非接触式激光束
9. 最大测量高度：1MM
10. SPC软件/SPC：Cpk.cp.xbar R&S
11. 计算机系统：MS-Win7 Pro
12. 软件语言版本：简/繁体中文、英文
13. 电源：单相AC 220V,60/50HZ
14. 重量：75kg
15. 设备外型尺寸：870(W)x700(D)x420(H)MM

1. Tiptop measure precision: 0.001MM
2. Repetitive accuracy: ±0.005MM
3. Lens magnification: 3X
4. Optics inspection system : 1.3 million pixel color CCD
5. Lase system: Laser module with glowing
6. Platform system : Full-automatic
7. platform size: 350×450MM
7. Measuring principle: Non-touch laser bean
8. Max measure height : 1MM
9. SPC software/ SPC: Cpk . Cp.Xbar R&S
10. Computer system: MS-Wi n7 P ro
11. Software language: Simplified Chinese, traditional Chinese, English
12. Power Source : Single-phase AC220V, 60/50HZ
13. Weight: 75kg
14. Product shape size: 870(W)x700(D) x420 (H) MM

3D 效果图/Renderings



CPK 报表/CPK report

